

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
CHEN-HUA YU	07/19/2016
HAO-YI TSAI	07/19/2016
TZU-SUNG HUANG	07/19/2018
MING-HUNG TSENG	07/19/2016
HUNG-YI KUO	07/19/2016
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<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16132688
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<b>SIGNATURE:</b>	/Daniel R. McClure/
<b>DATE SIGNED:</b>	09/17/2018
<b>Total Attachments: 2</b>	

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# ASSIGNMENT

WHEREAS, Chen-Hua YU, Hao-Yi TSAI, Tzu-Sung HUANG, Ming-Hung TSENG, and Hung-Yi KUO

hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: PACKAGED SEMICONDUCTOR DEVICES WITH WIRELESS CHARGING MEANS

Filed: \_\_\_\_\_ Serial No. \_\_\_\_\_

Executed on: \_\_\_\_\_

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd., of No. 8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu 300-78, Taiwan R.O.C., hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

ASSIGNMENT

7/19/16

Date

Name: Chen-Hua YU

(Last name: YU)

7.19.2016

Date

Name: Hao-Yi TSAI

(Last name: TSAI)

2016.7.19

Date

Name: Tzu-Sung HUANG

(Last name: HUANG)

2016.7.19

Date

Name: Ming-Hung TSENG

(Last name: TSENG)

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Name: Hung-Yi KUO

(Last name: KUO)